Special Issue

New Frontiers in Magnetic Polishing and Electrochemical Technology

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This special issue welcomes novel processing research submissions, such as miniaturization, precision, composite, intelligent, multiple physical coupling, simulation analysis, difficult-to-machine appearance and inner hole feature processing, new material processing technology, etc., we hope that experts and scholars can contribute your researches to this special issue. Thanks a lot.

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Deadline for manuscript submissions

closed (30 April 2022)



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Editor-in-Chief

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